SN54ACT533, SN74ACT533 OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

SCAS553C - NOVEMBER 1995 - REVISED OCTOBER 2002

- 4.5-V to 5.5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 11 ns at 5 V
- Inputs Are TTL-Voltage Compatible
- 3-State Inverting Outputs Drive Bus Lines Directly

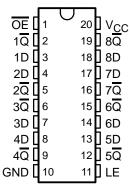
description/ordering information

The 'ACT533 devices are octal transparent D-type latches with 3-state outputs. When the latch-enable (LE) input is high, the $\overline{\mathbb{Q}}$ outputs follow the complements of the data (D) inputs. When LE is taken low, the $\overline{\mathbb{Q}}$ outputs are latched at the inverted levels set up at the D inputs.

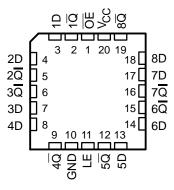
A buffered output-enable (OE) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

OE does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

SN54ACT533 . . . J OR W PACKAGE SN74ACT533 . . . DB, DW, N, NS, OR PW PACKAGE (TOP VIEW)



SN54ACT533 . . . FK PACKAGE (TOP VIEW)



To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

TA	PACKAGI	<u>=</u> †	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74ACT533N	SN74ACT533N
	SOIC - DW	Tube	SN74ACT533DW	ACT533
-40°C to 85°C	30IC - DW	Tape and reel	SN74ACT533DWR	AC1555
-40 C to 65 C	SOP - NS	Tape and reel	SN74ACT533NSR	ACT533
	SSOP – DB	Tape and reel	SN74ACT533DBR	AD533
	TSSOP – PW	Tape and reel	SN74ACT533PWR	AD533
	CDIP – J	Tube	SNJ54ACT533J	SNJ54ACT533J
–55°C to 125°C	CFP – W	Tube	SNJ54ACT533W	SNJ54ACT533W
	LCCC – FK	Tube	SNJ54ACT533K	SNJ54ACT533FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

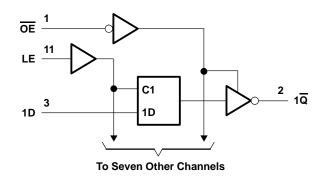


SCAS553C - NOVEMBER 1995 - REVISED OCTOBER 2002

FUNCTION TABLE (each latch)

	INPUTS		ОИТРИТ
OE	LE	D	Q
L	Н	Н	L
L	Н	L	Н
L	L	Χ	\overline{Q}_0
Н	X	Χ	Z

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input voltage range, V _I (see Note 1)		
Output voltage range, VO (see Note 1)		–0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)		±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CO}	c)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	- 	±50 mA
Continuous current through V _{CC} or GND		±200 mA
Package thermal impedance, θ_{JA} (see Note 2):	: DB package	70°C/W
	DW package	58°C/W
	N package	69°C/W
	NS package	60°C/W
	PW package	83°C/W
Storage temperature range, T _{stq}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



SCAS553C - NOVEMBER 1995 - REVISED OCTOBER 2002

recommended operating conditions (see Note 3)

		SN54ACT5		SN74A	CT533	UNIT
		MIN	MAX	MIN	MAX	ONII
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	7	2		V
VIL	Low-level input voltage		0.8		0.8	V
٧ _I	Input voltage	0	Vcc	0	VCC	V
٧o	Output voltage	0	Vcc	0	VCC	V
IOH	High-level output current	22	-24		-24	mA
l _{OL}	Low-level output current	70/	24		24	mA
Δt/Δν	Input transition rise or fall rate	Q	8		8	ns/V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST SOMBITIONS	, , , , , , , , , , , , , , , , , , ,	T,	_A = 25°C	;	SN54A	CT533	SN74A	CT533	
PARAMETER	TEST CONDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	Jan = 50 uA	4.5 V	4.4	4.49		4.4		4.4		
	I _{OH} = -50 μA	5.5 V	5.4	5.49		5.4		5.4		
\/a	1011 = 24 mA	4.5 V	3.86			3.7		3.76		V
VOH	I _{OH} = -24 mA	5.5 V	4.86			4.7		4.76		V
	I _{OH} = -50 mA [†]	5.5 V				3.85				
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V					3	3.85		
	I _{OL} = 50 μA	4.5 V			0.1		0.1		0.1	
	ΙΟΣ = 30 μΑ	5.5 V			0.1		0.1		0.1	
V _{OL}	I _{OL} = 24 mA	4.5 V			0.36	4	0.5		0.44	V
VOL		5.5 V			0.36	27/	0.5		0.44	V
	I _{OL} = 50 mA [†]	5.5 V				70	1.65			
	I _{OL} = 75 mA [†]	5.5 V				10			1.65	
loz	$V_O = V_{CC}$ or GND	5.5 V			±0.25		±5		±2.5	μΑ
Ι _Ι	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			4		80		40	μΑ
Δlcc [‡]	One input at 3.4 V, Other inputs at GND or V _{CC}	5.5 V		0.6			1.6		1.5	mA
Ci	$V_I = V_{CC}$ or GND	5 V		4.5					·	pF

Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

		T _A = 25°C		SN54ACT533		SN74ACT533		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	UNIT
t _W	Pulse duration, LE high	5		7.5	100	6		ns
t _{su}	Setup time, data before LE↓	3		5.5	11/2	4		ns
t _h	Hold time, data after LE↓	2		4		2.5		ns



[‡] This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

SN54ACT533, SN74ACT533 OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

SCAS553C - NOVEMBER 1995 - REVISED OCTOBER 2002

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

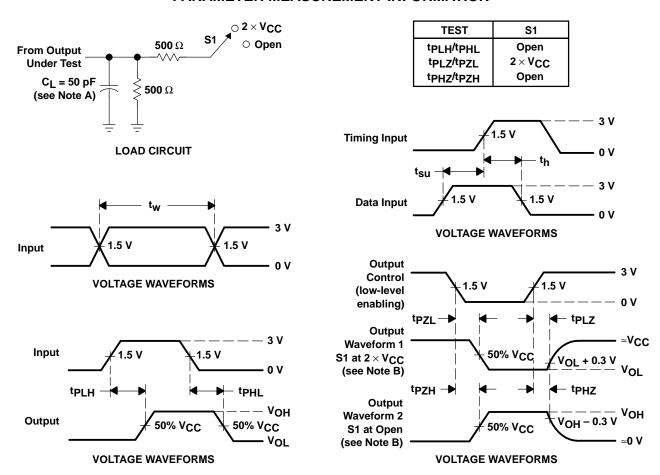
PARAMETER	FROM	ТО	T _A = 1	25°C	SN54A	CT533	SN74A	CT533	UNIT	
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	ONIT	
^t PLH	D	lα	2.5	10.5	1.5	13	2	11.5	ns	
^t PHL	D	Q	2.5	10	1.5	12.5	2	11	115	
^t PLH	LE	lα	2.5	10.5	1.5	13	2	11.5	ns	
^t PHL	LL	[2.5	10.5	1.5	13	2	11.5	115	
^t PZH	<u>OE</u>	ρl	2	10	(ب	12.5	1.5	11	ns	
^t PZL	ÜE	σ	2	10)1 (C	12.5	1.5	11	115	
^t PHZ	ŌĒ	Ια	2	10	Ø 1	12.5	1.5	11	nc	
^t PLZ	OE	ų į	2	10	1	12.5	1.5	11	ns	

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CO	TYP	UNIT	
C _{pd}	Power dissipation capacitance	C _L = 50 pF,	f = 1 MHz	40	pF

SCAS553C - NOVEMBER 1995 - REVISED OCTOBER 2002

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_Q = 50 \ \Omega$, $t_f \leq 2.5 \ ns$, $t_f \leq 2.5 \ ns$.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





4-Jun-2007

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)	
SN74ACT533DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI	
SN74ACT533DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ACT533DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ACT533DBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ACT533DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ACT533DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ACT533DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ACT533DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ACT533DWRE4	DWRE4 ACTIVE SOIC DW 20 2000 Green (RoHS & CU no Sb/Br)		CU NIPDAU	Level-1-260C-UNLIM					
SN74ACT533DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ACT533N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ACT533NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ACT533NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ACT533NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ACT533NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ACT533PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ACT533PWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ACT533PWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ACT533PWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI	
SN74ACT533PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ACT533PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ACT533PWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

(1) The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.



PACKAGE OPTION ADDENDUM

4-Jun-2007

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

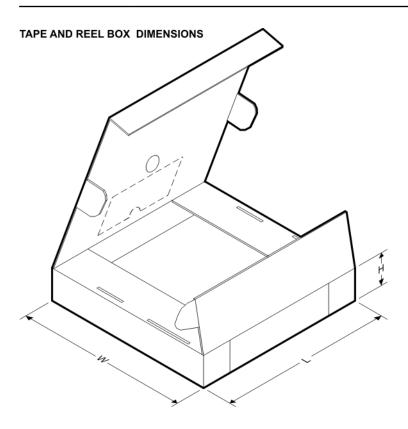
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ACT533DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ACT533DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ACT533PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1





*All dimensions are nominal

ı	7 III GIITTOTTOTOTTO GITO TTOTTITTGI								
	Device	Package Type Package Drawing		Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
	SN74ACT533DBR	SSOP	DB	20	2000	346.0	346.0	33.0	
	SN74ACT533DWR	SOIC	DW	20	2000	346.0	346.0	41.0	
	SN74ACT533PWR	TSSOP	PW	20	2000	346.0	346.0	33.0	

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products Amplifiers amplifier.ti.com Data Converters dataconverter.ti.com DSP dsp.ti.com Clocks and Timers www.ti.com/clocks Interface interface.ti.com Logic logic.ti.com Power Mgmt power.ti.com Microcontrollers microcontroller.ti.com www.ti-rfid.com RF/IF and ZigBee® Solutions www.ti.com/lprf

Applications	
Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2008, Texas Instruments Incorporated